

25V PNP HIGH PERFORMANCE TRANSISTOR IN SOT223

Features

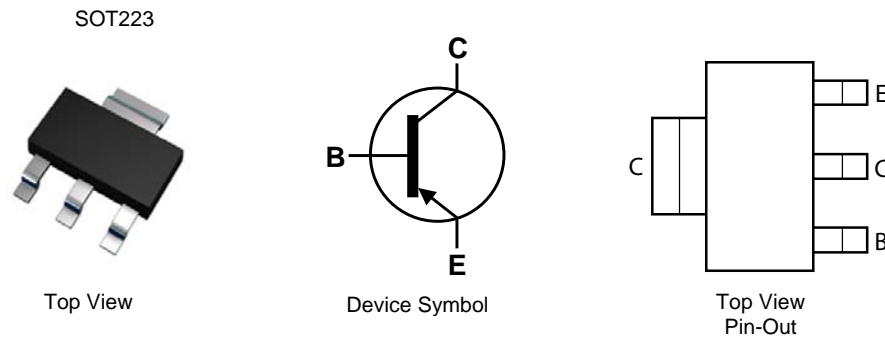
- $BV_{CEO} > -25V$
- $I_C = -3A$ High Continuous Current
- $I_{CM} = -8A$ Peak Pulse Current
- Low Saturation Voltage $V_{CE(sat)} < -300mV @ -1A$
- Complementary NPN Type: FZT649
- **Lead-Free Finish; RoHS compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP capable (Note 4)**

Mechanical Data

- Case: SOT223
- Case material: molded plastic. "Green" molding compound.
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208^(e3)
- Weight: 0.112 grams (approximate)

Applications

- MOSFET and IGBT Gate Driving

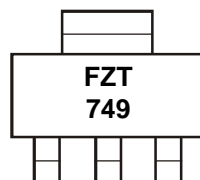


Ordering Information (Notes 4 & 5)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
FZT749TA	AEC-Q101	FZT749	7	12	1,000
FZT749QTA	Automotive	FZT749	7	12	1,000
FZT749TC	AEC-Q101	FZT749	13	12	4,000
FZT749QTC	Automotive	FZT749	13	12	4,000

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified.
 5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



FZT749 = Product Type Marking Code

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CB0}	-35	V
Collector-Emitter Voltage	V _{CEO}	-25	V
Emitter-Base Voltage	V _{EBO}	-7	V
Continuous Collector Current	I _C	-3	A
Peak Pulse Current	I _{CM}	-8	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

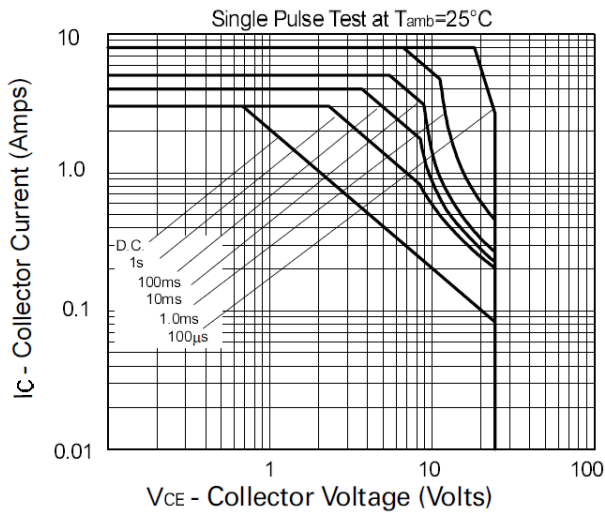
Characteristic	Symbol	Value	Unit
Power Dissipation	P _D	2	W
		3	W
Thermal Resistance, Junction to Ambient	R _{θJA}	62.5	°C/W
		41.7	°C/W
Thermal Resistance, Junction to Lead	R _{θJL}	12.93	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 9)

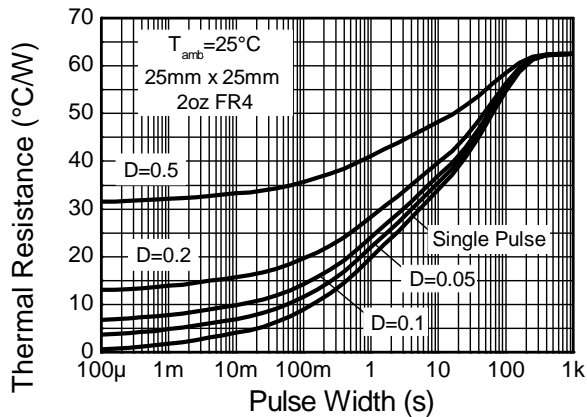
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	≥ 4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	≥ 400	V	C

- Notes:
6. For a device mounted with the collector lead on 25mm x 25mm 1oz copper that is on a single-sided FR4 PCB; device is measured under still air when conditions whilst operating in steady-state.
 7. Same as note (6), except the device is mounted on 50mm x 50mm 2oz copper.
 8. Thermal resistance from junction to solder-point (at the end of the collector lead).
 9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

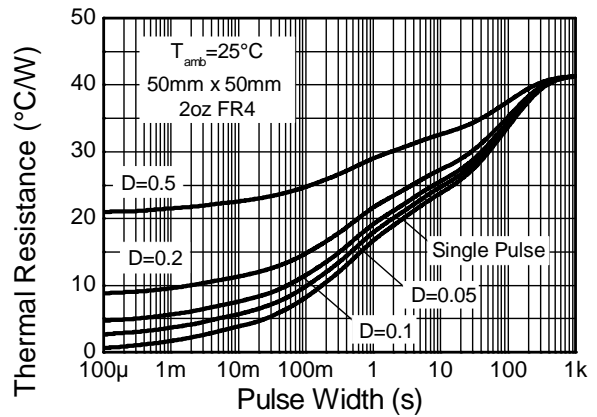
Thermal Characteristics and Derating Information



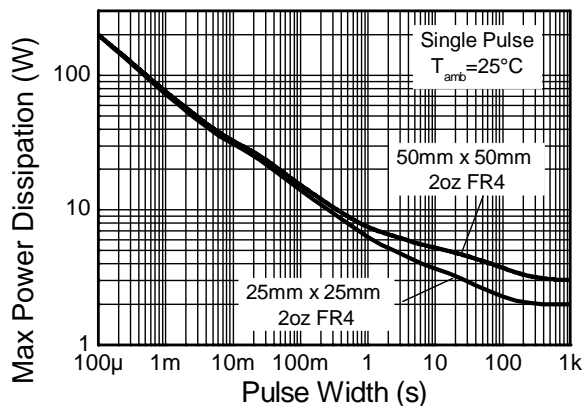
Safe Operating Area



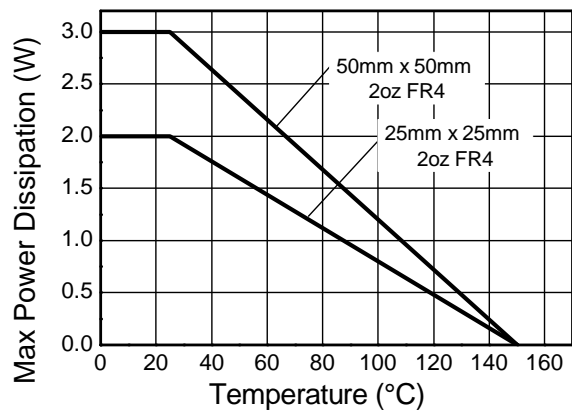
Transient Thermal Impedance



Transient Thermal Impedance



Pulse Power Dissipation



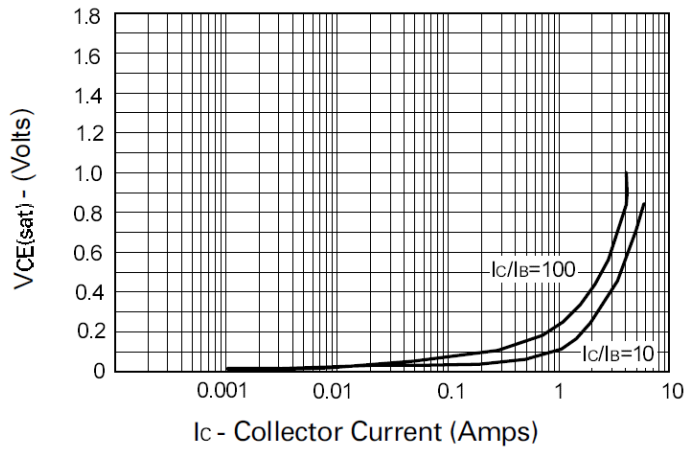
Derating Curve

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

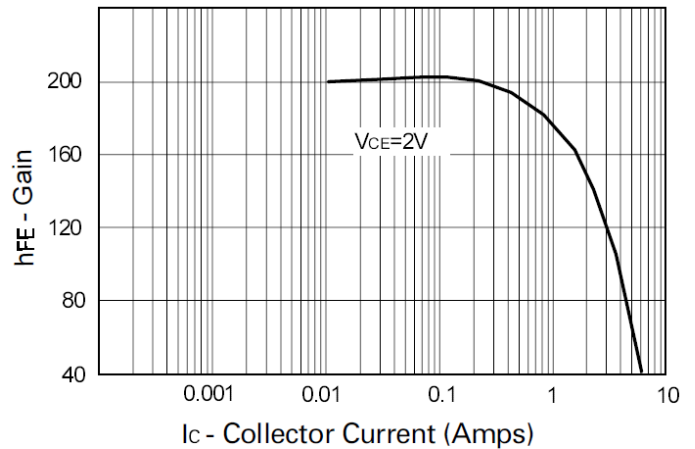
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV_{CBO}	-35	—	—	V	$I_C = -100\mu\text{A}$
Collector-Emitter Breakdown Voltage (Note 11)	BV_{CEO}	-25	—	—	V	$I_C = -10\text{mA}$
Emitter-Base Breakdown Voltage	BV_{EBO}	-7	—	—	V	$I_E = -100\mu\text{A}$
Collector Cut-off Current	I_{CBO}	—	<1	-100	nA	$V_{CB} = -30\text{V}$
		—	—	-10	μA	$V_{CB} = -30\text{V}, T_{AMB} = +100^\circ\text{C}$
Emitter Cut-off Current	I_{EBO}	—	<1	-100	nA	$V_{EB} = -5.6\text{V}$
Collector-Emitter Saturation Voltage (Note 11)	$V_{CE(SAT)}$	—	-0.12	-0.3	V	$I_C = -1\text{A}, I_B = -100\text{mA}$
		—	-0.40	-0.6		$I_C = -3\text{A}, I_B = -300\text{mA}$
Base-Emitter Saturation Voltage (Note 11)	$V_{CE(SAT)}$	—	-0.9	-1.25	V	$I_C = -1\text{A}, I_B = -100\text{mA}$
Base-Emitter Turn-On Voltage (Note 11)	$V_{BE(ON)}$	—	-0.8	-1.0	V	$I_C = -1\text{A}, V_{CE} = -2\text{V}$
DC Current Gain (Note 11)	h_{FE}	70	200	—	—	$I_C = -50\text{mA}, V_{CE} = -2\text{V}$
		100	200	300		$I_C = -1\text{A}, V_{CE} = -2\text{V}$
		75	570	—		$I_C = -2\text{A}, V_{CE} = -2\text{V}$
		15	50	—		$I_C = -6\text{A}, V_{CE} = -2\text{V}$
Current Gain-Bandwidth Product (Note 11)	f_T	100	160	—	MHz	$V_{CE} = -5\text{V}, I_C = -100\text{mA}$ $f = 100\text{MHz}$
Turn-On Time	t_{on}	—	40	—	ns	$V_{CC} = -10\text{V}, I_C = -500\text{mA}$
Turn-Off Time	t_{off}	—	450	—	ns	$I_{B1} = I_{B2} = -50\text{mA}$
Output Capacitance (Note 11)	C_{obo}	—	55	100	pF	$V_{CB} = -10\text{V}, f = 1\text{MHz}$

Note: 11. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.

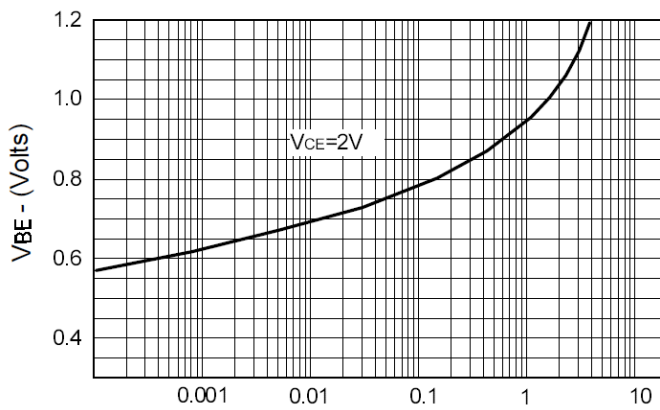
Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)



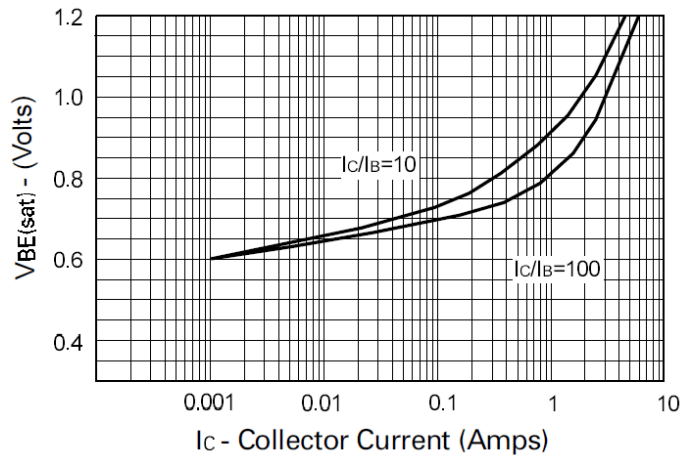
VCE(sat) v IC



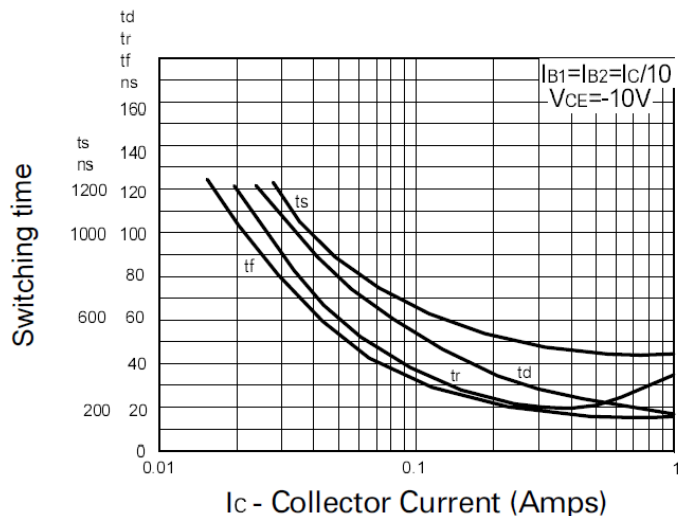
hFE v IC



VBE(on) v IC



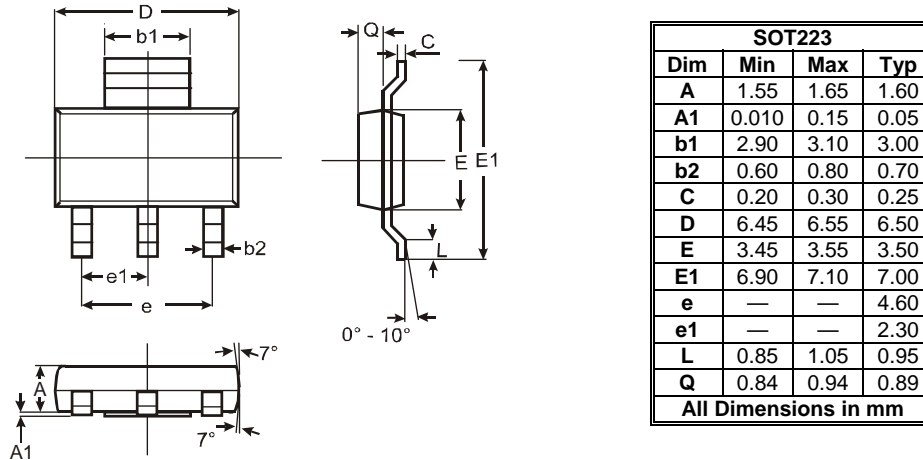
VBE(sat) v IC



Switching Speeds

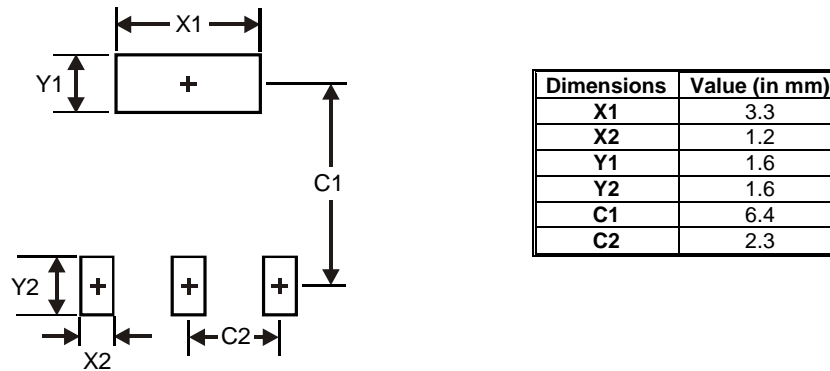
Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



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